

IN THE CLAIMS:

Please cancel claims 3-12 without prejudice to or disclaimer of the subject matter recited therein.

Please amend claim 1 as follows:

LISTING OF CURRENT CLAIMS

Claim 1. (Currently Amended) A thin type BGA semiconductor package comprising:

5 a composite substrate including a wiring board and a dummy die; die having a metal film, wherein the wiring board has an upper surface, a lower surface and an opening, the opening passes through the upper surface and the lower surface, a step is formed in the opening, a plurality of ball pads are formed on the lower surface, a plurality of connecting pads are formed on the step and electrically connect with the ball pads, the dummy die is has a first surface and a second surface, the first surface is attached to the lower surface of the wiring board and covers covering the opening to form a chip cavity; cavity, the metal film is formed over the second surface of the dummy die;

10 an integrated circuit chip disposed in the chip cavity, the chip having an active surface and a back surface, a plurality of bonding pads being formed on the active surface and electrically connected to the connecting pads of the wiring board, the back surface of the chip being attached to the dummy die;

15 a package body formed in the chip cavity of the composite substrate; and a plurality of solder balls on the ball pads.

Claim 2. (Original) The package of claim 1, wherein the dummy die has a thickness smaller than the diameter of the solder balls.

Claims 3-12. (Canceled)